



Specification

规格书

Light Source Module 5-12W

HL-LE2835W28Q56-H-A (AC 220V/50HZ)

Client approval 客户审核			Hongli approval 鸿利光电审核		
Approval 核准	Audit 确认	Confirmation 制作	Approval 核准	Audit 确认	Confirmation 制作
<input type="checkbox"/> Qualified 接受		<input type="checkbox"/> Disquali- 不接受	DATE: 日期:		

Adr: Airport High-tech Industry Base Jinggu South Road(XianKe 1st Road Intersec-
tion),

Huadu District, Guangzhou, China

地址: 中国广州市花都区机场高科技产业基地金谷南路与先科一路交汇

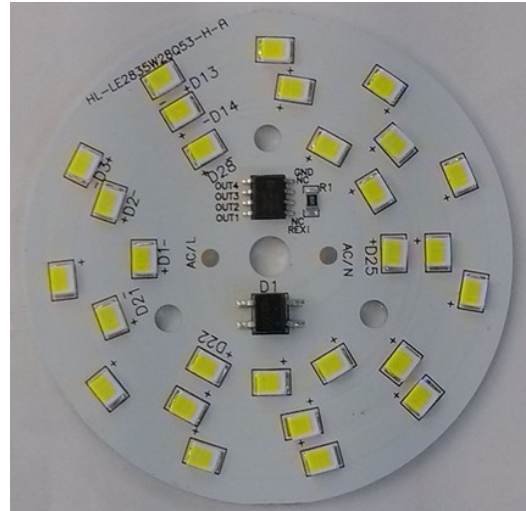
Tel/电话: 020-86733333

Fax/传真: 020-86733883
86733938 86733265

Web/网址: www.honglitronic.com

Description 描述

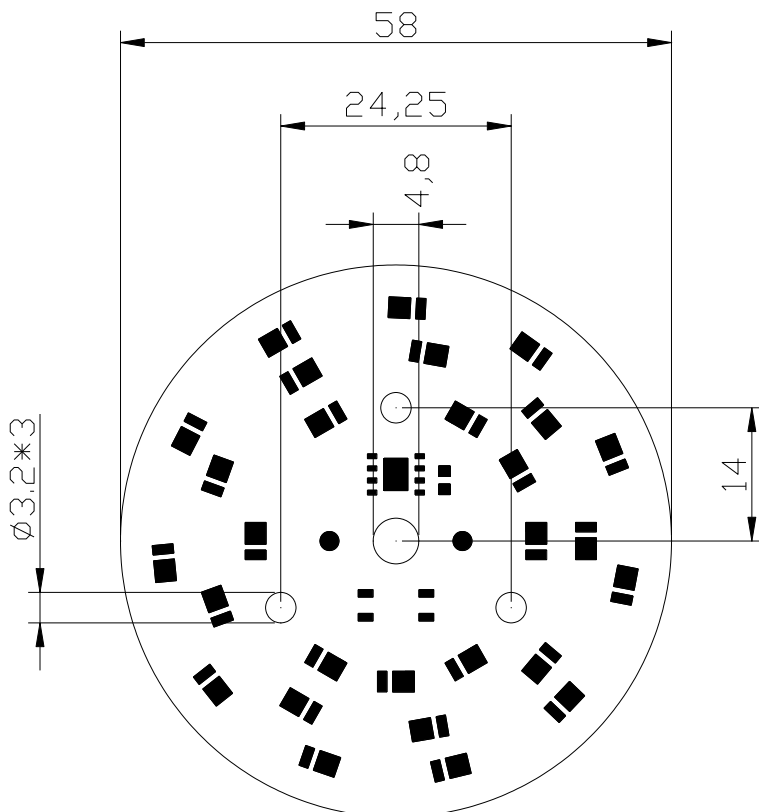
- Dimension $\varnothing 58\text{mm} \times 1.0\text{mm}$
尺寸： $\varnothing 58\text{mm} \times 1.0\text{mm}$
- 5W Directly to AC Power (AC 220V/50HZ)
- PF > 0.98 THD: < 16%
- CRI: Ra 80 typ 显色指数: 80 (最小)
- Luminous Flux: 520lm @ 22mA (平均)
- Wide viewing angle : 120°
发光角度: 120°
- Lambertian radiation pattern 朗伯光照模式
- RHOS compliant (ROHS标准).



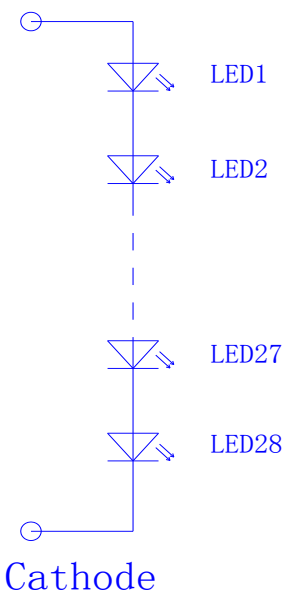
Applications 应用

- Bulb Light 球泡灯
- Down Light 筒灯
- Absorb dome light 吸顶灯

Outline Dimensions (mm) 尺寸



Anode



Notes:

1. All dimension units are millimeters (所有单位为毫米)。
2. All dimension tolerance is $\pm 0.2\text{mm}$ unless otherwise



Performance Parameters 性能参数

(1) Absolute Maximum Ratings at AC 220V TA=25°C

Parameter	Symbol	Rating	Units
Input Power 最大输入功率	Pi	5.6	W
DC Forward Current 额定电流	I _F	22	mA
Peak Forward Current 峰值电流	I _{Fp}	30	mA
Junction Temperature 结温	T _j	120°C	
Operating Temperature Range 操作温度	Topr	-20°C To +75°C	
Storage Temperature Range 储存温度	Tstg	-40°C To +100°C	
Lead Soldering Temperature 引线焊接温度	Tsol	Max 350°C for 5 sec Max	

Note (注意):

- 1.1/10 Duty Cycle,0.1ms Pulse Width.脉冲宽度≤0.1毫秒 占空比≤1/10.
- 2.The temperature of Aluminum PCB do not exceed 55°C □ 基板正负极引线温度不能超过55°C.
- 3.When hand soldering, keep the temperature of iron below less 300°C less than 3seconds.
当手工焊接时,烙铁的温度必须小于300°C,时间不能超过3秒.

(2) Electrical / Optical Characteristics at AC 220 TA=25°C

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Color Temperature[4]	TC	5500	6000	6500	K	IF=25mA
Color-rendering index	Ra	80	—	—	—	IF=25mA
Forward Voltage [1]	VF	230	246	264	V	IF=25mA
thermal resistance	Rth	—	4.3	—	°C/W	IF=25mA
Luminous Flux	Φ _v	—	520	—	lm	IF=25mA
Power dissipation	Pd	4.7	5	5.6	W	IF=25mA

Note:

- 1.The tolerance of measurement at our tester is VF+/-3% , Φ_v+/-10% and Ra+/-1.测试仪测量的公差在电压±3% , 流明±10% 和显指±1.

(3) Device Selection Guide

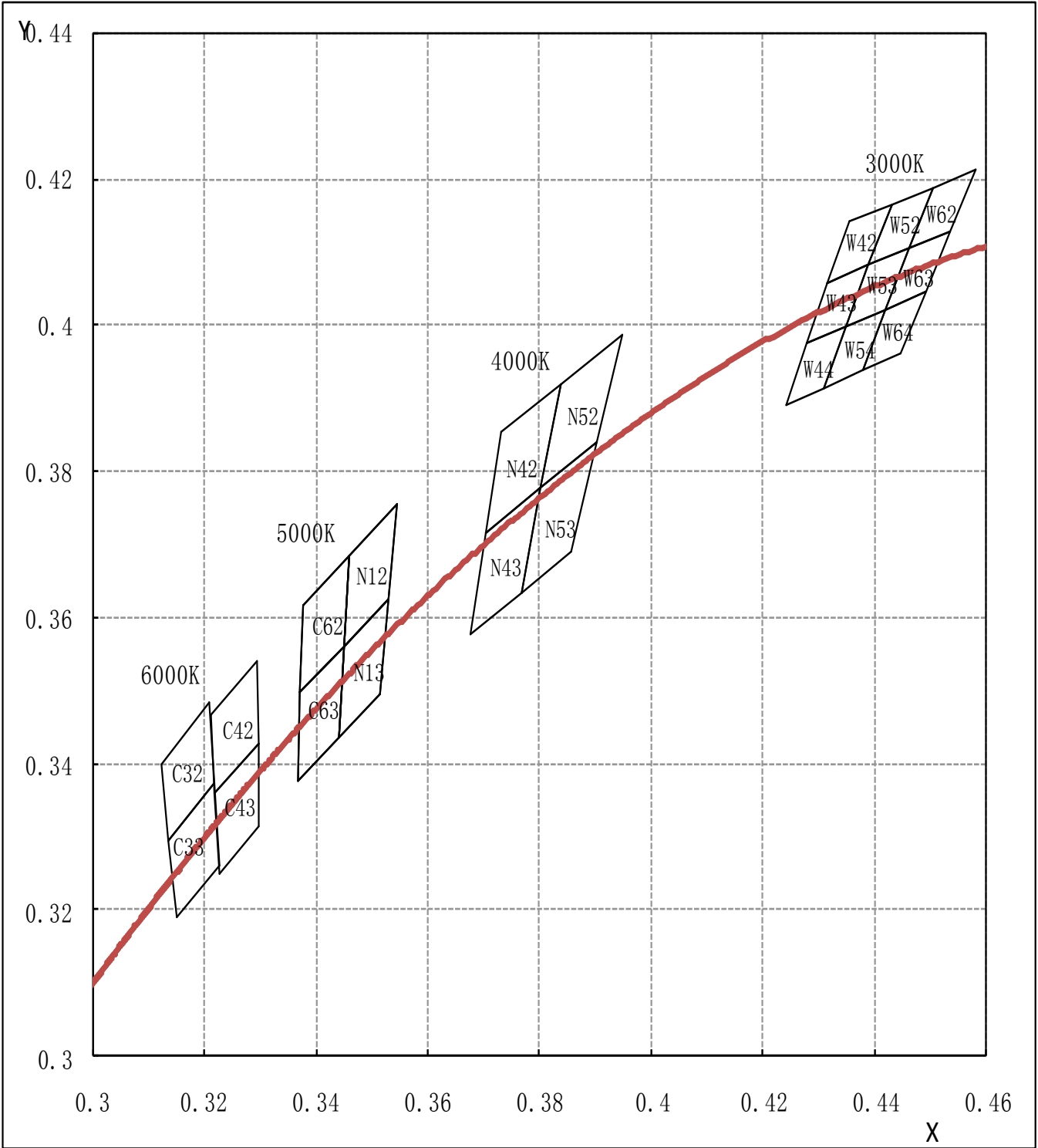
Part No.	Chip		Lens Type	
	Material	Emitting Color		
HL-LE2835W28Q56-5B1C28 (Ra2)	InGaN	Blue	Warm White	Orange Diffused



Under Development	●
Mass production	

Product bins

1、Chromaticity bins



2、Bin Range of Chromaticlcity Coordlnate Bin区分类及色坐标范围

CCT 色温	Bin Code Bin代码	CIE_x	CIE_y	Bin Code Bin代码	CIE_x	CIE_y
3000K	W42 3000-3100K	0.4354	0.4142	W43 3000-3100K	0.4316	0.4059
		0.4430	0.4165		0.4390	0.4082
		0.4390	0.4082		0.4350	0.3998
		0.4316	0.4059		0.4279	0.3975
	W44 3000-3100K	0.4279	0.3975	W52 2900-3000K	0.4430	0.4165
		0.4350	0.3998		0.4505	0.4189
		0.4310	0.3915		0.4463	0.4106
		0.4241	0.3892		0.4390	0.4082
	W53 2900-3000K	0.4390	0.4082	W54 2900-3000K	0.4350	0.3998
		0.4463	0.4106		0.4420	0.4022
		0.4420	0.4022		0.4378	0.3939
		0.4350	0.3998		0.4310	0.3915
	W62 2800-2900K	0.4505	0.4189	W63 2800-2900K	0.4463	0.4106
		0.4581	0.4212		0.4536	0.4129
		0.4536	0.4129		0.4492	0.4045
		0.4463	0.4106		0.4420	0.4022
W64 2800-2900K	0.4420	0.4022				
	0.4492	0.4045				
	0.4447	0.3962				
	0.4378	0.3939				



2、Bin Range of Chromaticlcty Coordinatnate Bin区分类及色坐标范围

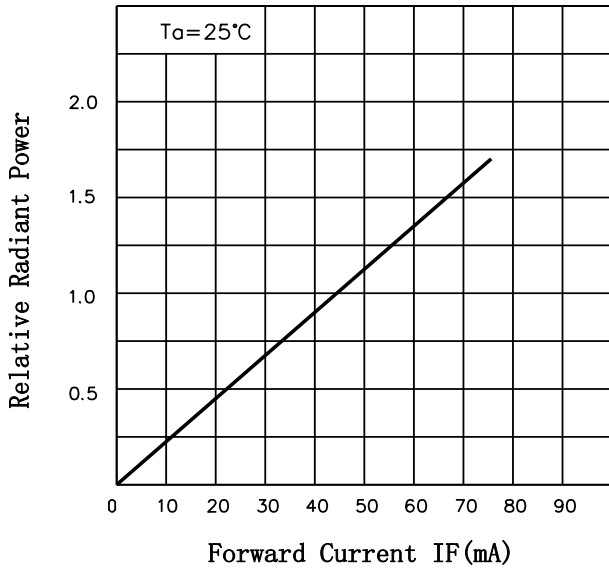
CCT 色温	Bin Code Bin代码	CIE_x	CIE_y	Bin Code Bin代码	CIE_x	CIE_y
4000K	N42 4000-4250K	0.3731	0.3853	N52 3800-4000K	0.3839	0.3920
		0.3839	0.3920		0.3947	0.3987
		0.3803	0.3777		0.3903	0.3839
		0.3703	0.3716		0.3803	0.3777
		0.3703	0.3716		0.3803	0.3777
	N43 4000-4250K	0.3803	0.3777	N53 3800-4000K	0.3903	0.3839
		0.3767	0.3634		0.3858	0.3690
		0.3675	0.3578		0.3767	0.3634
		0.3376	0.3616		0.3461	0.3685
		0.3461	0.3685		0.3545	0.3754
5000K	C62 5000-5300K	0.3451	0.3561	N12 4750-5000K	0.3530	0.3625
		0.3372	0.3497		0.3451	0.3561
		0.3372	0.3497		0.3451	0.3561
		0.3451	0.3561		0.3530	0.3625
		0.3441	0.3437		0.3514	0.3496
	C63 5000-5300K	0.3368	0.3378	N13 4750-5000K	0.3441	0.3437
		0.3205	0.3481		0.3211	0.3468
		0.3117	0.3393		0.3294	0.3542
		0.3131	0.329		0.3296	0.3429
		0.3213	0.3371		0.3219	0.3360
6000K	C32 6000-6500K	0.3213	0.3371	C42 5700-6000K	0.3219	0.3360
		0.3131	0.329		0.3296	0.3429
		0.3150	0.3190		0.3298	0.3315
	C33 6000-6500K	0.3226	0.3262	C43 5700-6000K	0.3227	0.3251



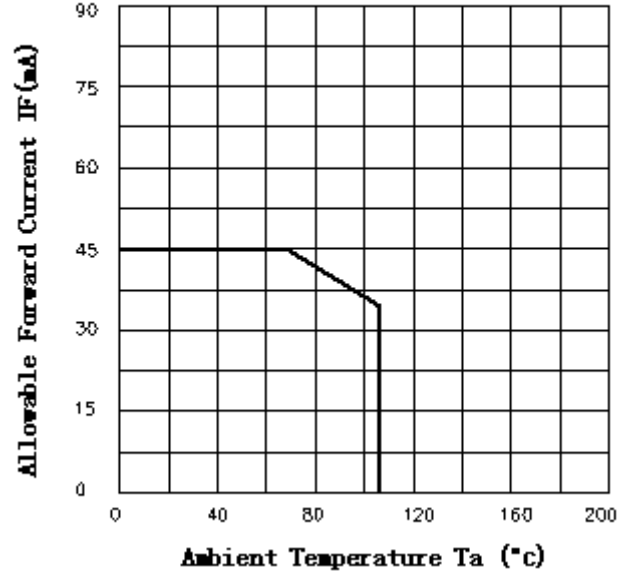
Under Development	●
Mass production	□

Spatial Distribution Graph 光学特性曲线分布图

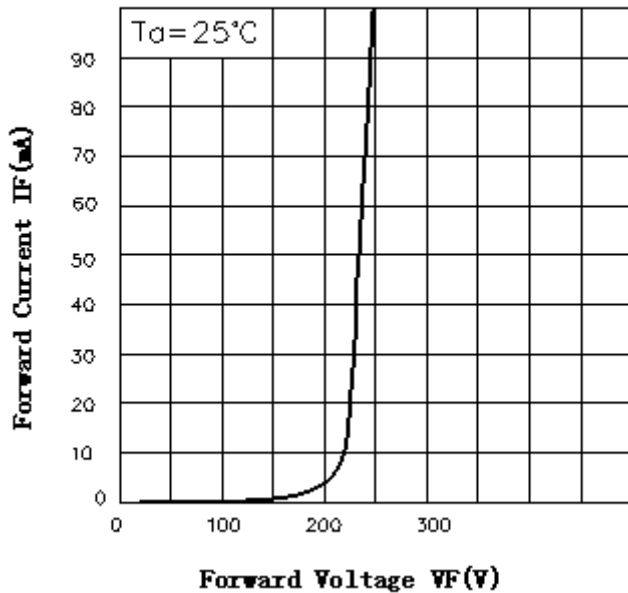
Relative Radiant Power-IF
正向电流与相对辐射功率



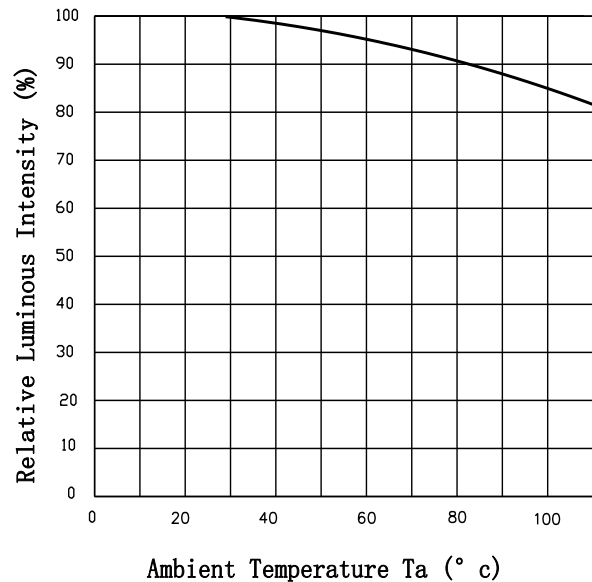
Allowable Forward Current - Ta
环境温度与正向电流曲线图



IF - VF
伏安特性曲线图

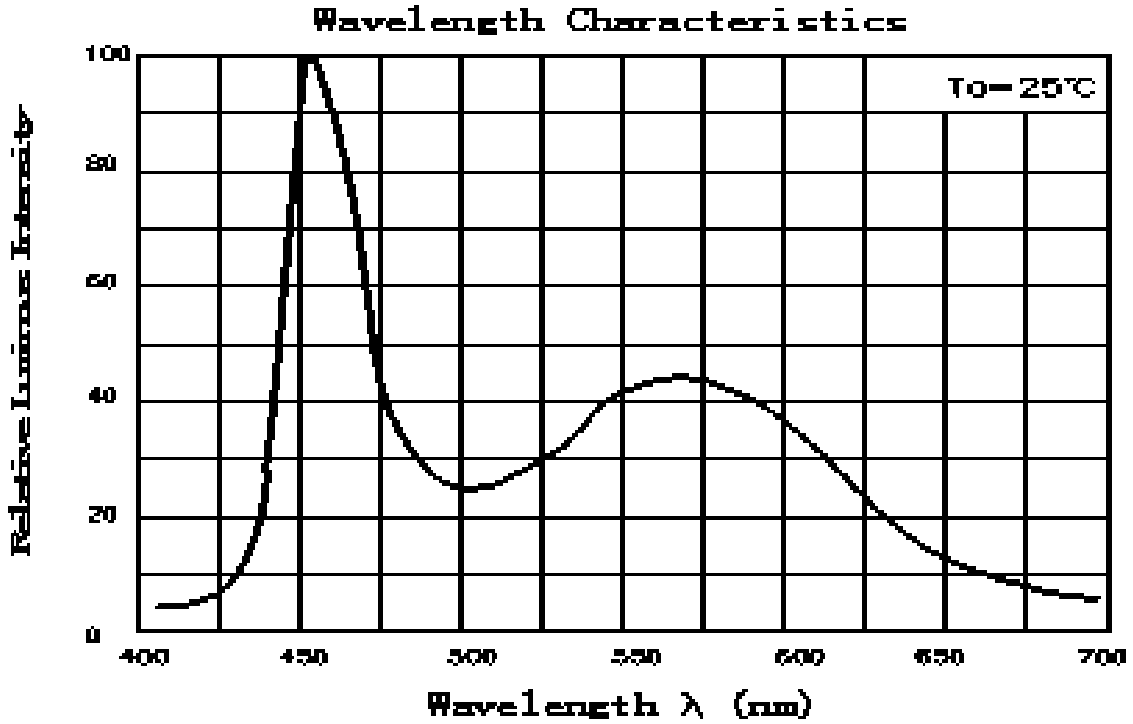


Relative Luminous Intensity - Ta
结点温度与相对流明曲线图

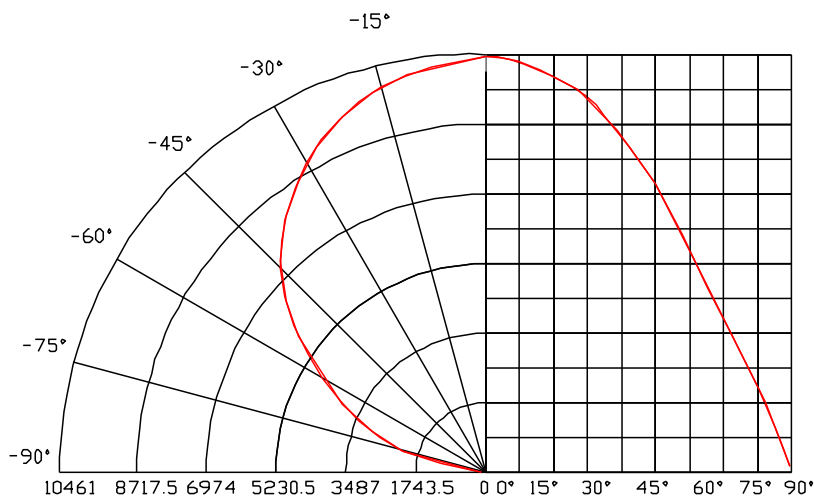




Under Development	●
Mass production	□



Spatial Distribution Graph 辐射特性曲线图





EMI test report 电磁兼容测试报告

EMI Conduction Test

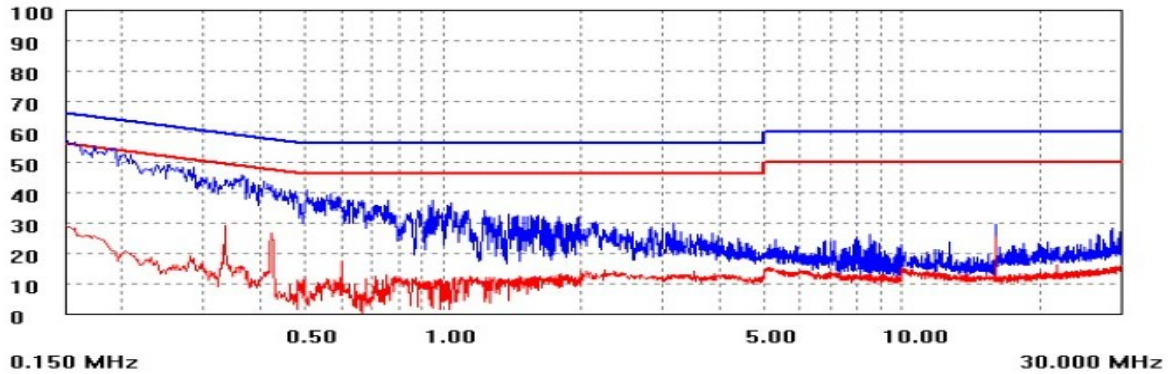
1、 Vin=220Vac L 线测试结果

EMI TEST REPORT

Organization: sm	Operator: zhuxingan	EUT:	parameter
Place:	Time: 2012/10/23/17:16	Test equipment: KH3935	
Detector: PK+AV	Test-time(ms): 20	SN: 1135217	
Limit: EN55022B	Transductor(PK/AV): PK-1 / AV-1		
Remark:			

Start(MHz)	End(MHz)	Step(MHz)	freq, step
0.150	2.000	0.002	
2.000	10.000	0.010	
10.000	30.000	0.025	

dBuV scan resul



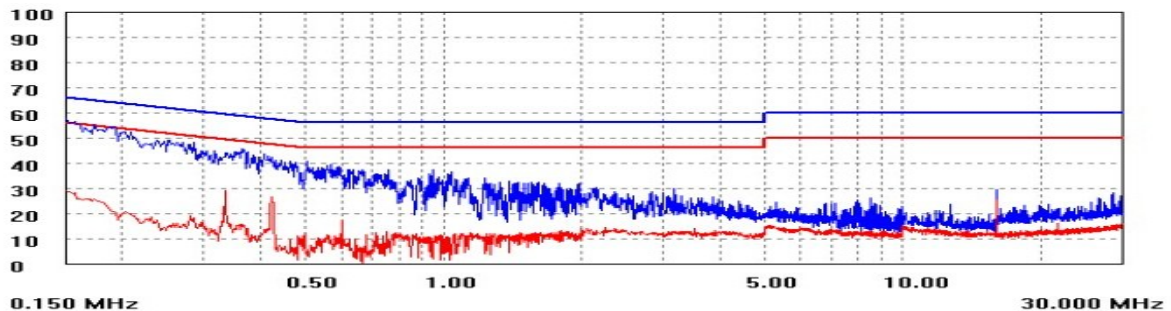
2、 Vin=220Vac N 线测试结

EMI TEST REPORT

Organization: sm	Operator: zhuxingan	EUT:	parameter
Place:	Time: 2012/10/23/17:16	Test equipment: KH3935	
Detector: PK+AV	Test-time(ms): 20	SN: 1135217	
Limit: EN55022B	Transductor(PK/AV): PK-1 / AV-1		
Remark:			

Start(MHz)	End(MHz)	Step(MHz)	freq, step
0.150	2.000	0.002	
2.000	10.000	0.010	
10.000	30.000	0.025	

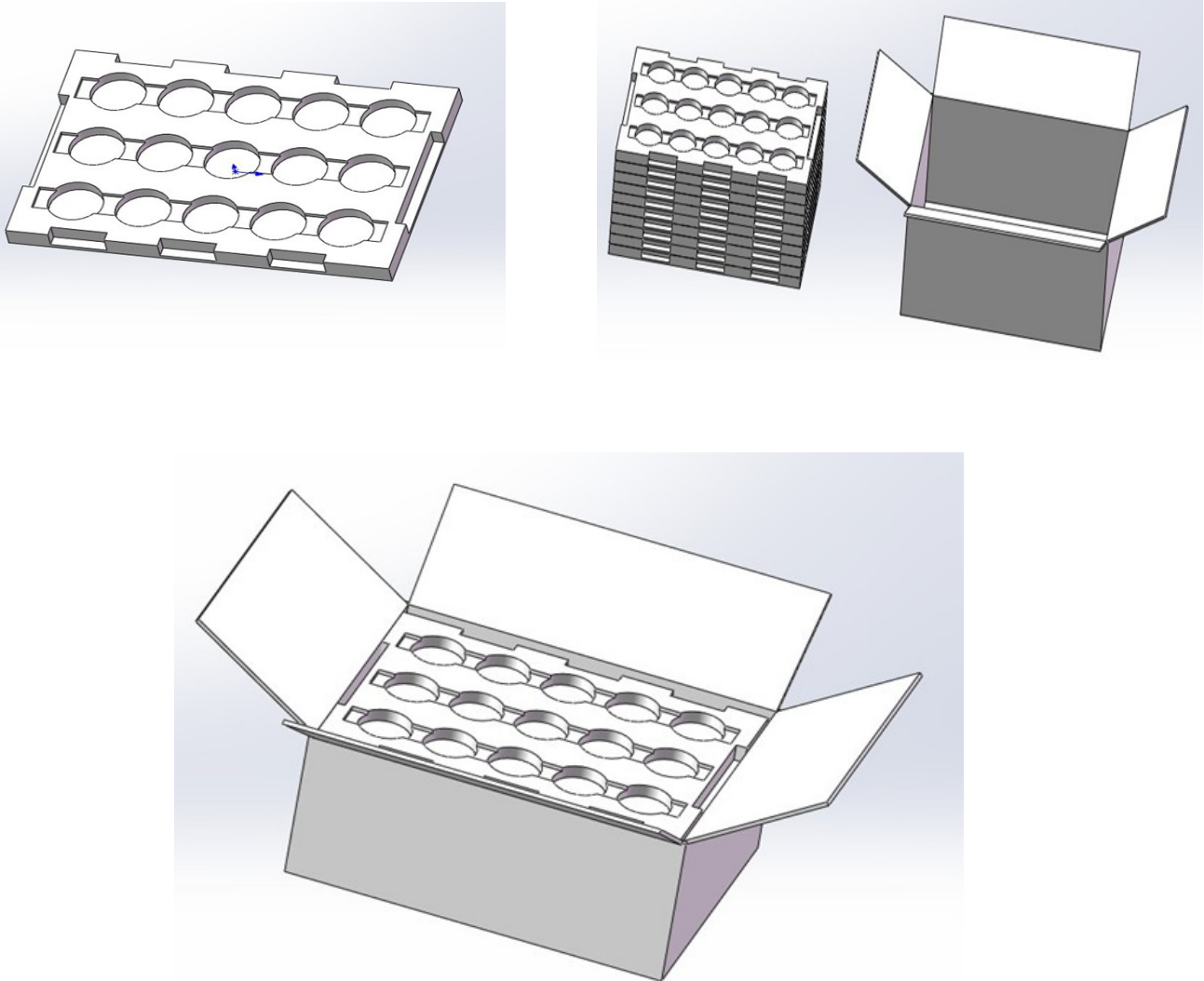
dBuV scan resul





Under Development	●
Mass production	

Tray Packaging 托盘包装



1Box:75PCS Per tray * Max 10 layer = 750PCS (about 10kg)

Box size (L*W*H) = 410*320*185MM

Precaution for use (防护措施)

1. Storage 储存

To avoid the moisture penetration ,we recommend storing LEDs in a dry box (or a desiccator) with a desiccant. The recommended conditions are temperature 5 to 30 degrees Centigrade. Humidity 60% maximum.避免湿气的渗透,我们建议 LED储存 在干燥的盒子里(或干燥器中)并放置干燥剂.建议的条件是温度5~30℃,相对湿度不能超过60%.

2.Precaution after opening packing 拆包后的注意事项:

2.1.Soldering should be done right after opening the package (within 24Hrs).

拆包后24小时内必须焊接完成.

2.2.Keeping of a fraction.剩余部分

-Sealing密封.

-Temperature: 5~30℃ Humidity: less than 30%温度:5~30℃ ,相对湿度不能超过 30%.

2.3.If the package has been opened than 1 week or the color of desiccant changed, components should be dried for 10-12 Hrs at 60±5℃.如果开封超过一周或 湿度标示卡发生改变,元件必须在 60±5℃条件下进行12小时除湿.

3. Hand Soldering手动焊接

Be careful because the damage of the product is often started at the time of the hand soldering.

产品的损害往往是在开始手动焊接时不小心导致的。在开始手动焊接时，需小心避免对产品造成损害。

Stress on the LEDs should be avoided during heating in soldering process. Please do not force over 1000g impact or pressure diagonally on the silicone lens. It will cause fatal damage on this product.

在焊接加热过程中应避免应力作用在LED灯珠上。不要施加超过1000克的力于硅胶透镜上,那样容易对产品造成损伤.

After soldering, do not deal with the product before its temperature drop down to room temperature.

焊接后，不能将产品迅速冷却至室温。

This product is not adaptable reflow process.此产品不能过回流焊

4. Cleaning清洗

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30℃ for 3 minutes or 50℃ for 30 seconds. When using other solvents, it should be confirmed be-forehand whether the solvents will dissolve the package and the silicone or not.

焊接后建议用酒精作为清洗溶剂，洗清时应在30℃三分钟或50℃持续30秒，当使用其它溶剂时，应事先确认此溶剂是否会与产品有机硅发生溶解。

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pre-test should be done to confirm whether any damage to LEDs will occur.

超声波也是一种有效的清洗方式，但超声波清洗的程度依赖于诸多因素，比如超声波功率，一般来说，超声波功率不应超过300W，在清洗前请确认此清洗方法是否会对LED产品造成损害。

5. Static Electricity 防静电保护

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current., even not light. 静电与冲击电压都会损坏LED产品，损坏后的LED灯将产生一系列的不良后果，如正向电压偏低、发光二极管漏电甚至死灯。

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.所有的设备器材都必须接地保护，同时，建议佩戴静电环或防静电手套，当使用LED灯时应使用防静电容器。

6. Design Consideration 设计考虑

In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. When the LEDs are illuminating, operating current should be decided after considering the plastic surface maximum temperature.

在设计电路时，电流通过每个LED灯时一定不能超过指定的最大额定值，同时应采用电阻保护，否则电压波动过大将导致涌浪电流，可能会使LED灯烧坏。LED点亮时，需考虑到LED可承受的最大胶面温度。

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

直接查看发光中的LED灯，特别是发光强度大的，对我们的眼睛会造成非常大的损害。

Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.

热设计是极为重要的，因为热量的产生可能导致产品性能衰减，如亮度下降、色偏移等。所以在设计LED灯具时，应考虑散热问题。

In the use of screws, you need to pay attention to LED damaged, need to be careful; installation, you can use clip-type to install, to avoid damage!

使用螺丝安装时请注意，方法不当可能导致LED灯的损害，您可以使用卡扣的方式来安装LED灯，以避免损坏LED。